

02-09-2001

Docket No.: 55563

FORM PTO-1595 (Modified)
(Rev. 6-93)
OMB No. 0651-0011 (exp. 4/94)
Copyright 1996-97 LegalStar
POSA/REV02



101609778

SHEET

U.S. DEPARTMENT OF COMMERCE
Patent and Trademark Office

.Y

1.30.01

Tab settings

To the Honorable Commissioner of Patents and Trademarks: Please record the attached original documents or copy thereof.

1. Name of conveying party(ies):

Ming-Hsun LEE
Chin-Te CHEN

Additional names(s) of conveying party(ies) Yes No

2. Name and address of receiving party(ies):

Siliconware Precision Industries

Name: Co., Ltd.

Address: No. 123, Sec. 3, Da Fong Road

Tantzu

City: Taichung State/Prov.:

Country: Taiwan, R.O.C. ZIP:

Additional name(s) & address(es) Yes No

3. Nature of conveyance:

- Assignment Merger
- Security Agreement Change of Name
- Other

Execution Date: 08/07/00

4. Application number(s) or registration numbers(s):

If this document is being filed together with a new application, the execution date of the application is: 08/07/00

Patent Application No. Filing date

02/02/2001 TGEDANU1 00000023 09774227

02 FC:581

40.00 00

B. Patent No.(s)

09774227

Additional numbers Yes No

5. Name and address of party to whom correspondence concerning document should be mailed:

Name: Peter F. Corless

Registration No. 33,860

Address: EDWARDS & ANGELL, LLP

Dike, Bronstein, Roberts & Cushman, IP Group

130 Water Street

City: Boston State/Prov.: MA

Country: U.S.A. ZIP: 02109

6. Total number of applications and patents involved:

1

7. Total fee (37 CFR 3.41):.....\$ 40.00

Enclosed - Any excess or insufficiency should be credited or debited to deposit account

Authorized to be charged to deposit account

8. Deposit account number:

04-1105

DO NOT USE THIS SPACE

9. Statement and signature.

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

Peter F. Corless

Name of Person Signing

Signature

1/29/01

Date

2

Total number of pages including cover sheet, attachments, and

ASSIGNMENT OF U.S. PATENT APPLICATION

In consideration of the sum of One Dollar (\$1.00) in hand paid, and other good and valuable consideration, the receipt of which is hereby acknowledged, the undersigned

(1) Ming-Hsun LEE (2) Chin-Te CHEN

Inventor(s) Full Name(s)

.....

hereby sell, assign and transfer to

SILICONWARE PRECISION INDUSTRIES CO., LTD.

Assignee Name and Address

No. 123, Sec. 3, Da Fong Rd., Tantz, Taichung, Taiwan, R.O.C.

(hereinafter called the Assignee) the entire right, title, and interest in and to any and all improvements which are disclosed in the Application for United States Letters Patent entitled

" MUTLI-CHIP MODULE AND METHOD OF FABRICATING THE SAME

Title of Invention

which application was

Complete either a) or b)

a) executed by the undersigned on the day of, 19

b) filed on the day of, 19

Serial No

including any and all United States Letters Patents which may be granted therefore and any and all extensions, divisions, reissues, substitutes, renewals or continuations thereof, and the right to all benefits under the International Convention for the Protection of Industrial Property.

It is hereby authorized and requested that the Commissioner of Patents issue any and all of said Letters Patent, when granted, to said Assignee.

Further, it is agreed that, when requested, without charge to but at the expense of said Assignee, the undersigned will execute all divisional, continuing, substitute, renewal, and reissue patent applications; execute all rightful other papers; and generally do everything possible which said Assignee shall consider desirable for aiding in securing and maintaining proper patent protection.

Date

Signed at Tantz, Taichung.....

this 7th day of August, 2000.....

Inventor(s) Full Signature(s)

INVENTOR(S):

Ming Hsun Lee

Chin-te Chen

Witnesses' Full Signatures

WITNESSES: